



PATENT

Case Docket No. MICRON.133DV1

Date: January 19, 2005

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s) : Trivedi et al.
Appl. No. : 10/038,305
Filed : January 2, 2002
For : METHOD OF FORMING A
DUAL DAMASCENE
INTERCONNECT BY
SELECTIVE METAL
DEPOSITION
Group Art Unit : 2813
Class/Sub-Class : 438-632000
Examiner : Thanh T. Nguyen

I hereby certify that this correspondence and all marked attachments are being deposited with the United States Postal Service as first class mail in an envelope addressed to: Mail Stop Issue Fee, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on

January 20, 2005

(Date)

Adeel S. Akhtar

Adeel S. Akhtar, Reg. No. 41,394

TRANSMITTAL LETTER

MAIL STOP ISSUE FEE
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

Enclosed for filing is the Issue Fee for the above-identified application:

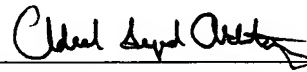
- (X) Form PTOL-85.
- (X) A check in the amount of \$1,730 to cover the issue fee, publication fee, and advanced order of copies is enclosed.
- (X) Comments on Statement of Reasons for Allowance.
- (X) Request for Consideration of Information Disclosure Statements, with copies of three earlier submitted Information Disclosure Statements and Forms PTO-1449.

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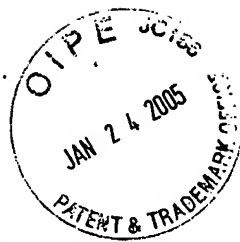
- (X) The Commissioner is hereby authorized to charge any additional fees which may be required, or credit any overpayment, to Account No. 11-1410.
- (X) Return prepaid postcard.



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CERTIFICATE OF MAILING

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Adeel S. Akhtar

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COMMENTS ON STATEMENT OF REASONS FOR ALLOWANCE

Mail Stop ISSUE FEE

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

Applicants appreciate the finding of the pending claims to be allowable. In the Reasons for Allowance accompanying the Notice of Allowability, the Examiner stated that "none of the prior art alone or in combination teaches or suggests the particular subset of the process steps in forming a dual damascene by selectively depositing a first metal over the conductive element relative to insulating surfaces of the dual damascene structure to partially fill the contact via, and filling a remainder of the contact via with a second metal, the second metal being more conductive than the first metal, wherein depositing the first metal comprises filling the contact via to a height between about one-third to two-thirds of a height of the contact via."

Applicants assume that, pursuant to M.P.E.P. § 1302.14, the Examiner has stated some, but not all, of the reasons for allowance of the claims and that, as a result, the statements discussed above do not necessarily relate to or completely set out the reasons for allowance of each and every claim. For example, not all claims recite "selectively" depositing a first metal relative to insulating surfaces. In addition, Applicants submit that the claims depending from independent Claims 6 and 17 recite additional limitations distinguishing the art of record.

Appl. No. : 10/038,305
Filed : January 2, 2002

Respectfully submitted,

KNOBBE, MARTENS, OLSON & BEAR, LLP

Dated: January 20, 2005

By: Adeel S. Akhtar

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